

G O D W I N G R U B E R

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Assistant Commissioner for Patents
Washington, D.C. 20231-9998

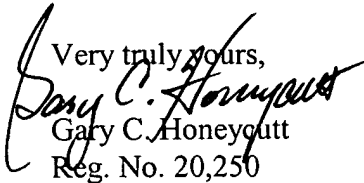
Re: Amendment 37 CFR 1.115
Title: **WAFER SCALE ASSEMBLY OF CHIP-SIZE PACKAGES**
Serial No.: 09/186,973
Filing date: 11/05/98
TI File No: TI-23158
Our File No: 50000.2065

Dear Sir:

Enclosed please find the following items relating to the above-identified patent:

- (1) Amendment 37 CFR 1.115;
- (2) Replacement Pages;
- (3) Petition for Extension of Time; and
- (4) Postcards.

Please return the date-stamped postcard to our offices at the above address. In the meantime if you have any questions or comments concerning this matter, please call the undersigned at your earliest convenience. Otherwise, please accept the enclosed.

Very truly yours,

Gary C. Honeycutt
Reg. No. 20,250

GCH/ecc
Enclosures
cc: Lawrence Bassuk, Texas Instruments Incorporated